

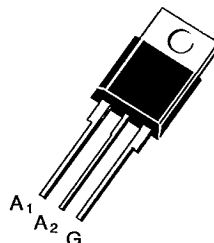
- GLASS PASSIVATED CHIP
- I_{GT} SPECIFIED IN FOUR QUADRANTS
- INSULATING VOLTAGE : 2500 V_{RMS}
- UL RECOGNIZED (E81734)

ADVANTAGES

- $I_H < 13$ mA
- HIGH SURGE CURRENT : $I_{TSM} = 100$ A

DESCRIPTION

Insulated triacs specified for light dimmer applications.



TO 220 AB
(Plastic)

ABSOLUTE RATINGS (limiting values)

Symbol	Parameter		Value	Unit
$I_{T(RMS)}$	RMS on-state Current (360° conduction angle)	$T_C = 85\text{ °C}$	6	A
I_{TSM}	Non Repetitive Surge Peak on-state Current (T_J initial = 25 °C - Half sine wave)	$t = 8.3\text{ ms}$	105	A
		$t = 10\text{ ms}$	100	
I^2t	I^2t Value for Fusing	$t = 10\text{ ms}$	50	A ² s
di/dt	Critical Rate of Rise of on-state Current (1)	Repetitive $F = 50\text{ Hz}$	10	A/μs
		Non Repetitive	50	
T_{stg} T_J	Storage and Operating Junction Temperature Range		- 40 to 125 - 40 to 110	°C °C

Symbol	Parameter	BTA 06--			Unit
		200GP	400GP	600GP	
V_{DRM}	Repetitive Peak off-state Voltage (2)	200	400	600	V

(1) $I_G = 750$ mA di/dt = 1 A/μs

(2) $T_J = 110\text{ °C}$.

THERMAL RESISTANCES

Symbol	Parameter	Value	Unit
$R_{th(j-a)}$	Junction to Ambient	60	°C/W
$R_{th(j-c)}\text{ DC}$	Junction to Case for DC	5.1	°C/W
$R_{th(j-c)}\text{ AC}$	Junction to Case for 360° Conduction Angle ($F = 50\text{ Hz}$)	3.8	°C/W

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GATE CHARACTERISTICS (maximum values)

 $P_{GM} = 40 \text{ W}$ ($t_p = 10 \mu\text{s}$) $I_{GM} = 4 \text{ A}$ ($t_p = 10 \mu\text{s}$) $P_{G(AV)} = 1 \text{ W}$ $V_{GM} = 16 \text{ V}$ ($t_p = 10 \mu\text{s}$)

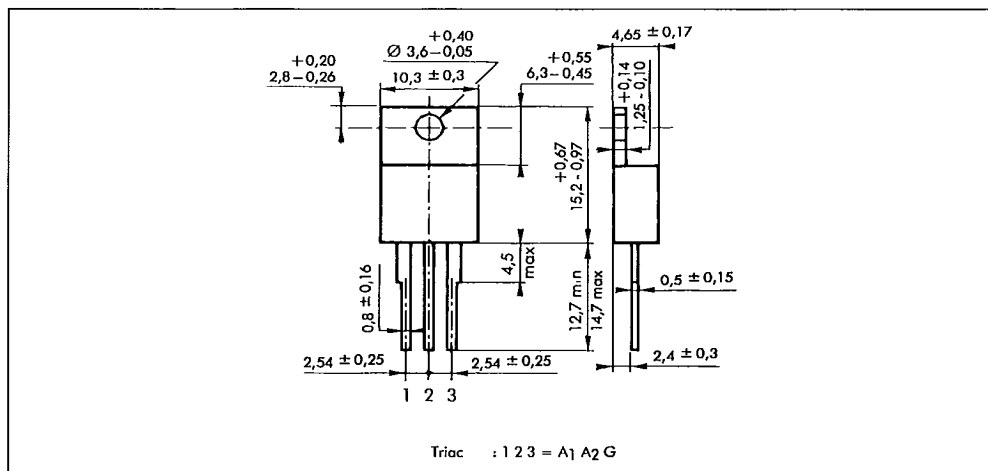
ELECTRICAL CHARACTERISTICS

Symbol	Test Conditions			Quadrants	Min.	Typ.	Max.	Unit
I_{GT}	$T_J = 25^\circ\text{C}$ Pulse Duration $> 20 \mu\text{s}$	$V_D = 12 \text{ V}$	$R_L = 33 \Omega$	I-II-III		15	50	mA
				IV		25	75	
V_{GT}	$T_J = 25^\circ\text{C}$ Pulse Duration $> 20 \mu\text{s}$	$V_D = 12 \text{ V}$	$R_L = 33 \Omega$	I-II-III-IV			1.5	V
V_{GD}	$T_J = 110^\circ\text{C}$	$V_D = V_{DRM}$	$R_L = 3.3 \text{ k}\Omega$	I-II-III-IV	0.2			V
I_{H^*}	$T_J = 25^\circ\text{C}$	$I_T = 100 \text{ mA}$	Gate Open				13	mA
I_L	$T_J = 25^\circ\text{C}$ Pulse Duration $> 20 \mu\text{s}$	$V_D = 12 \text{ V}$	$I_G = 150 \text{ mA}$	I-III-IV		25		mA
				II		50		
V_{TM}^*	$T_J = 25^\circ\text{C}$	$I_{TM} = 8.5 \text{ A}$	$t_p = 10 \text{ ms}$				1.4	V
I_{DRM}^*	V_{DRM} Specified	$T_J = 25^\circ\text{C}$					0.01	mA
		$T_J = 110^\circ\text{C}$					0.5	
dv/dt^*	$T_J = 110^\circ\text{C}$ Linear Slope up to $V_D = 67\% V_{DRM}$	Gate Open			30	100		V/ μs
$(dv/dt)_c^*$	$T_C = 85^\circ\text{C}$ $(di/dt)_c = 1.8 \text{ A/ms}$	$V_D = V_{DRM}$	$I_T = 8.5 \text{ A}$		1	10		V/ μs
t_{gt}	$T_J = 25^\circ\text{C}$ $I_G = 100 \text{ mA}$	$V_D = V_{DRM}$ $di_G/dt = 1 \text{ A}/\mu\text{s}$	$I_T = 8.5 \text{ A}$	I-II-III-IV		2		μs

* For either polarity of electrode A_2 voltage with reference to electrode A_1 .

PACKAGE MECHANICAL DATA

TO 220 AB Plastic



Cooling method : by conduction (method C)

Marking : type number

Weight : 2 g.

S G S-THOMSON

T-25-15

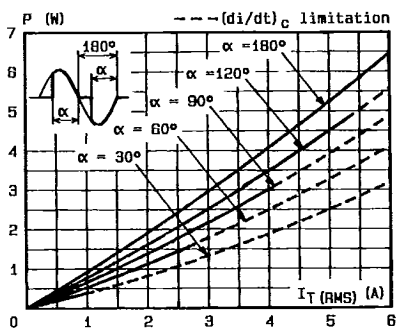


Fig.1 - Maximum mean power dissipation versus RMS on-state current ($F = 60$ Hz).

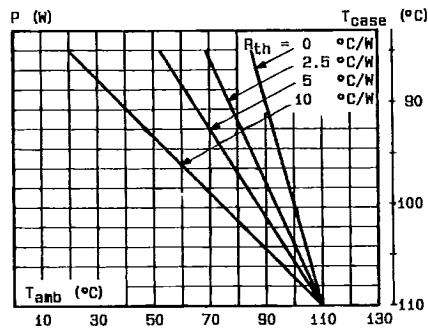


Fig.2 - Correlation between maximum mean power dissipation and maximum allowable temperatures (T_{amb} and T_{case}) for different thermal resistances heatsink + contact.

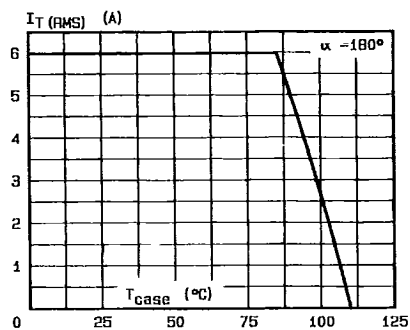


Fig.3 - RMS on-state current versus case temperature.

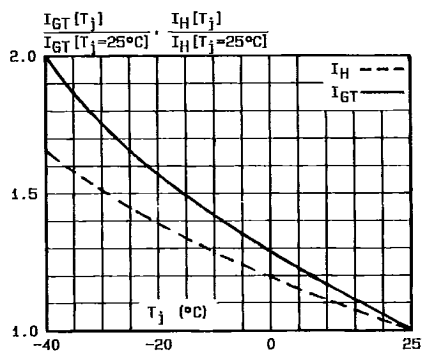


Fig.5 - Relative variation of gate trigger current and holding current versus junction temperature.

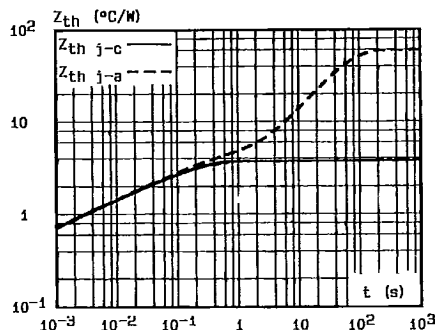


Fig.4 - Thermal transient impedance junction to case and junction to ambient versus pulse duration.

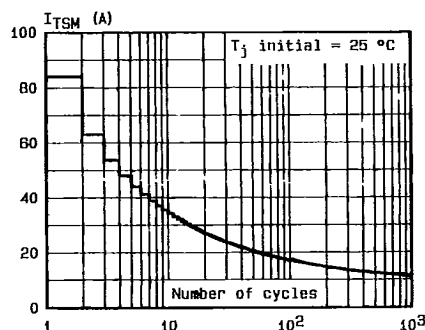


Fig.6 - Non repetitive surge peak on-state current versus number of cycles.

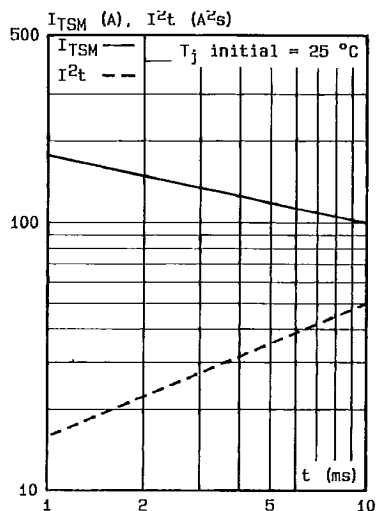


Fig.7 - Non repetitive surge peak on-state current for a sinusoidal pulse with width : $t \leq 10$ ms, and corresponding value of I^2t .

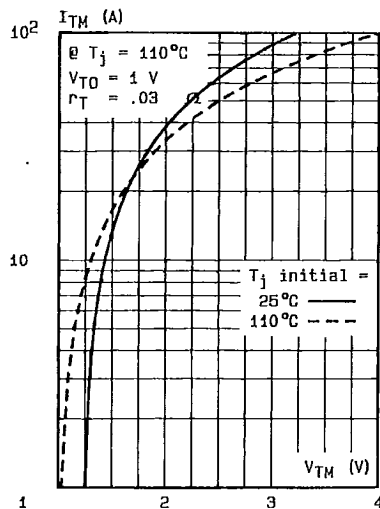


Fig.8 - On-state characteristics (maximum values)

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